Interference Search

EAST Search History 3/6/2005 ✗✗✗✗

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	21	((xray x-ray (x adj ray) radiation) and (detect$3 sens$3) and (support$3) and (panel substrate wafer plate film sheet layer) and (housing case casing enclosure container) and (reinforc$3) and (opening gap hole hollow recess protrusion)).clm.	US-PGPUB	OR	ON	2006/03/06 07:35
L4	19	((xray x-ray (x adj ray) radiation) and (detect$3 sens$3) and (support$3) and (panel substrate wafer plate film sheet layer) and (housing case casing enclosure container) and ((amount quantity dose dosage) with (xray x-ray (x adj ray) radiation)) and (opening gap hole hollow recess protrusion)).clm.	US-PGPUB	OR	ON	2006/03/06 07:35

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	314099	@pd>="20051207"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/01 09:31
S2	2171	(250/370.09 250/370.11 250/580 250/581 250/582).ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/01 09:32
S3	64	S1 and S2	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/01 09:47
S4	6978	(250/336.1 250/338.1 250/349 250/361R 250/366 250/369 250/370.01 250/370.08 250/394).ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/01 09:32
S5	1006135	(radiation xray x-ray x adj ray)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/01 09:33
S6	6763874	detect$3 sens$3 measur$3 measurement	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/01 09:33
S7	5459322	support$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/01 09:33
S8	2376841	substrate wafer	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/01 09:33

S9	2956829	imag$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/01 09:33
S10	7408021	gap hole opening hollow recess protrusion	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/01 09:33
S11	11566742	hous$3 case casing enclosure contain$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/01 09:33
S12	10461460	panel plate film sheet layer	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/01 09:33
S13	330875	(thermal temperature) with (expand$3 expansion)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/01 09:33
S14	1910488	(reinforc$3 reinforcement stabiliz$3 stabilization strengthen$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/01 09:34
S15	63991	honeycomb$3 honey-comb$3 (honey adj comb$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/01 09:34
S16	222810	cassette	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/01 09:34

EAST Search History

S17	1845847	(solid-state)(solid adj state) semiconductor semi-conductor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/01 09:34
S18	694463	weight with (reduc$3 reduction light$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/01 09:36
S19	5198	(S5 with S6) and S8 and S9 and (S10 with (S7 S8)) and S11 and S12	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/01 09:37
S20	295	S19 and ((S7 S14) with (S8 S12)) and (S5 with (S12 S16)) and (S18) and (S9 same S5)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/01 09:40
S21	1	S19 and (S15 with (S8 S12)) and (S17 same S6) and (S18 with (S8 S12 S16))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/01 09:47
S22	5	S19 and S4 and S1	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/01 09:47
S23	4561	((crevice or S10) with S7 with (S8 S12 member)) and (S5 with S6)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/01 10:15
S24	0	S20 and S4 and S1	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/01 09:47

EAST Search History

S25	1341	S23 and ("250" "378").clas.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/01 10:13
S26	968	S25 and @ad<="20040331"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/01 10:33
S27	632	S9 and S26	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/01 10:17
S28	0	("2004/0211909").URPN.	USPAT	OR	ON	2006/03/01 10:29
S29	336	S26 not S27	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/01 10:34
S30	373	S25 not (S26 S27)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/01 10:44
S31	0	Kengo-Emoto.in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/01 10:45
S32	44	Kengo-$.in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/01 10:47
S33	7200	g01t001/20.ipc.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/01 10:47

| S34 | 2567 | h01l031/09.ipc. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/03/01 10:47 |
| S35 | 40 | (S33 S34) and S23 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/03/01 10:48 |